

Electronic Supplementary Information for:

Controlling the Nanostructure of Bismuth Telluride by Selective Chemical Vapour Deposition from a Single Source Precursor

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Substrate preparation: Sputtered SiO₂ and TiN substrates and photolithographically patterned TiN/SiO₂ substrates were prepared as described previously.¹⁴ The E-beam lithography was carried out using a JEOL JBX-9300FS Electron beam Lithography System with a double-layered positive resist PMMA495. During exposure, the gun current was set to 4 nA with an accelerating voltage of 100 kV. The etching was performed by a RIE80+ with CHF₃ and Ar and the etch rate was found to be 0.37 nm s⁻¹.

Characterisation of nanocrystalline Bi₂Te₃: XRD measurements were carried out using a Rigaku Smartlab diffractometer with a 9 kW Cu-K_α source, parallel line focus incident beam and a DTex250 1D detector. Raman scattering spectra of the deposited films were measured at room temperature on a Renishaw InVia Micro Raman Spectrometer using a helium-neon laser with a wavelength of 633 nm. The incident laser power was adjusted to ~1 mW for all samples. SEM was performed using a Zeiss EVO LS 25 with an accelerating voltage of 10 kV, and EDX data were obtained with an Oxford INCAx-act X-ray detector, using a commercial sample of Bi₂Te₃ powder (Strem Chemicals, 99.99 %) as a reference. WDX was obtained with a ThermoFisher MagnaRay probe using NiC80 and PET X-ray diffracting crystals. High resolution SEM measurements were carried out with a field emission SEM (Jeol JSM 7500F) at an accelerating voltage of 2 kV. Microanalyses were undertaken by Medac Ltd. Hall effect measurements were performed at room temperature on a Nanometrics HL5500PC with a current of 1 mA under a field of 0.5 Tesla at 300 K. The Seebeck coefficient was determined using a custom-made Seebeck measurement unit, which was

calibrated against a polycrystalline Bi foil reference standard. The measurement accuracy was found to be within 5% and the system was calibrated using copper-constantan thermocouples and a high precision Keithley DMM 2000/E digital multimeter with 0.1% accuracy.

Thermogravimetric Analysis: Thermogravimetric analyses (TGA) used a Mettler Toledo TGA/SDTA851e analyser under a flow of Ar at 65 mL/min, contained within a dry, N₂-purged glove box. The temperature was increased at a rate of 10 °/min. TGA of [BiCl₃(TeⁿBu₂)₃] shows that mass loss occurs in three distinct steps at 100–150 °C, 170–270 °C and 300–340 °C, leaving a residual mass of 37% which is unchanged up to 600 °C (Fig. S1), with a shiny residue being observed in the crucible. This suggests a complex decomposition pathway, with Bi₂Te₃ being the final residue (theoretical residual mass = 38%). The TGA also indicates limited reagent evaporation occurs at ambient pressure.

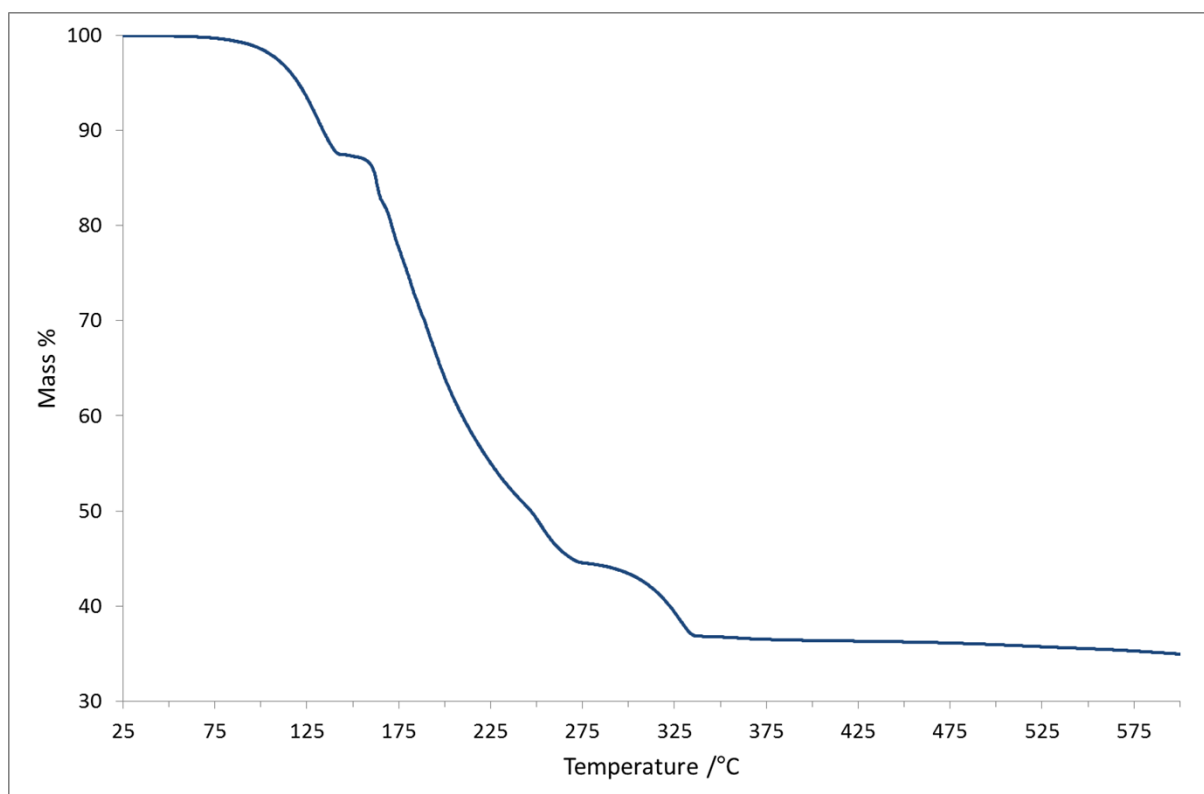
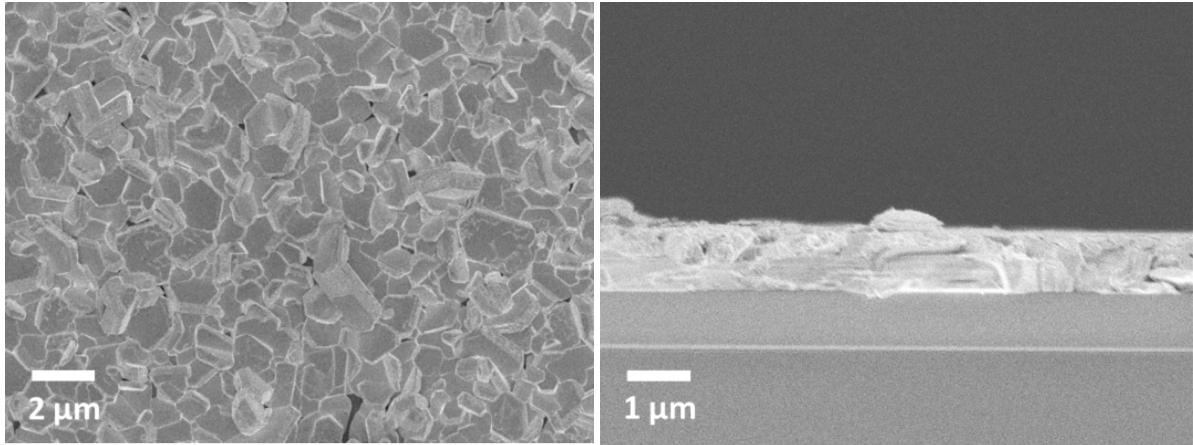


Figure S1. TGA plot for [BiCl₃(TeⁿBu₂)₃] collected under Ar with T_{ramp} = 10 °C/min.



(a)

(b)

Figure S2 (a). Top view of Bi_2Te_3 film deposited onto a TiN substrate (500 °C); **(b).** Cross sectional SEM of Bi_2Te_3 film deposited on SiO_2 substrate (500 °C)

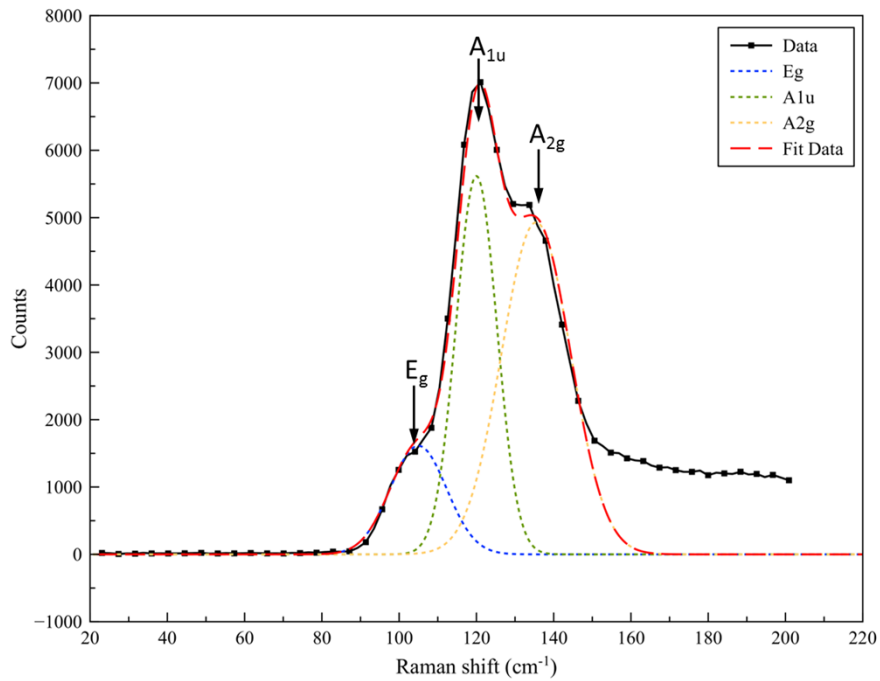


Figure S3. Raman spectrum of Bi_2Te_3 thin film formed by LPCVD from $[\text{BiCl}_3(\text{Te}^n\text{Bu}_2)_3]$ (black trace) and simulated fit (red trace). The broad features to high frequency are from the SiO_2 substrate.

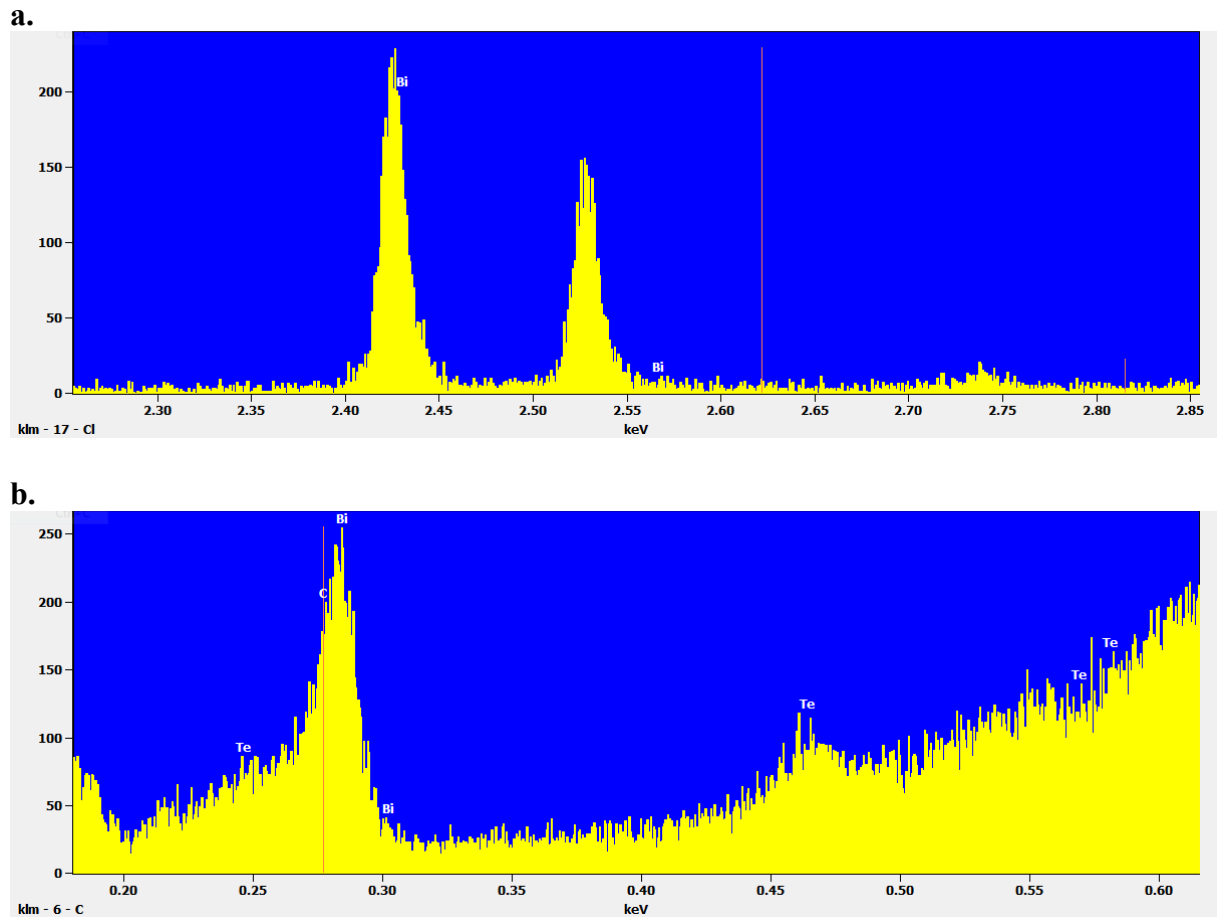


Figure S4. WDX spectra for a Bi_2Te_3 thin film over two energy windows. **a.** demonstrates the absence of a Cl $\text{K}\alpha$ or $\text{K}\beta$ peak (at the energies shown by the red lines), **b.** shows the overlapping C $\text{K}\alpha$ and Bi N6-N5 peaks.

Table S1: Lattice parameters for Bi_2Te_3 samples, refined from x-ray diffraction data against a literature pattern (ref. 19) using the PDXL programme.

| Sample (see Fig. 4) | a | c |
|-----------------------------|------------|------------|
| a. 100 μm well | * | 30.40(2) |
| b. SiO_2 substrate | 4.378(10) | 30.46(5) |
| c. TiN substrate | 4.3885(14) | 30.444(13) |
| d. Literature (ref. 19) | 4.3849 | 30.4971 |

* the a lattice parameter could not be refined from this data as only 0 0 l peaks were observed

Microfocus and pole figure XRD analysis of microscale Bi_2Te_3 arrays

9 data sets were collected with a 50 micron beam centred on wells of different sizes (100 μm (regions 1,2,3), 60 μm (regions 4,5,6) and 40 μm (regions 7,8,9) as indicated in Figure S6a). Data are dominated by 0 0 l reflections with $l = 6, 15, 18$ and 21 showing a high degree of c -axis orientation. The data sets are very similar (Figure S6b), except that overall peak intensities are clearly grouped into 3 different values based on the well size (Figure S6b inset).

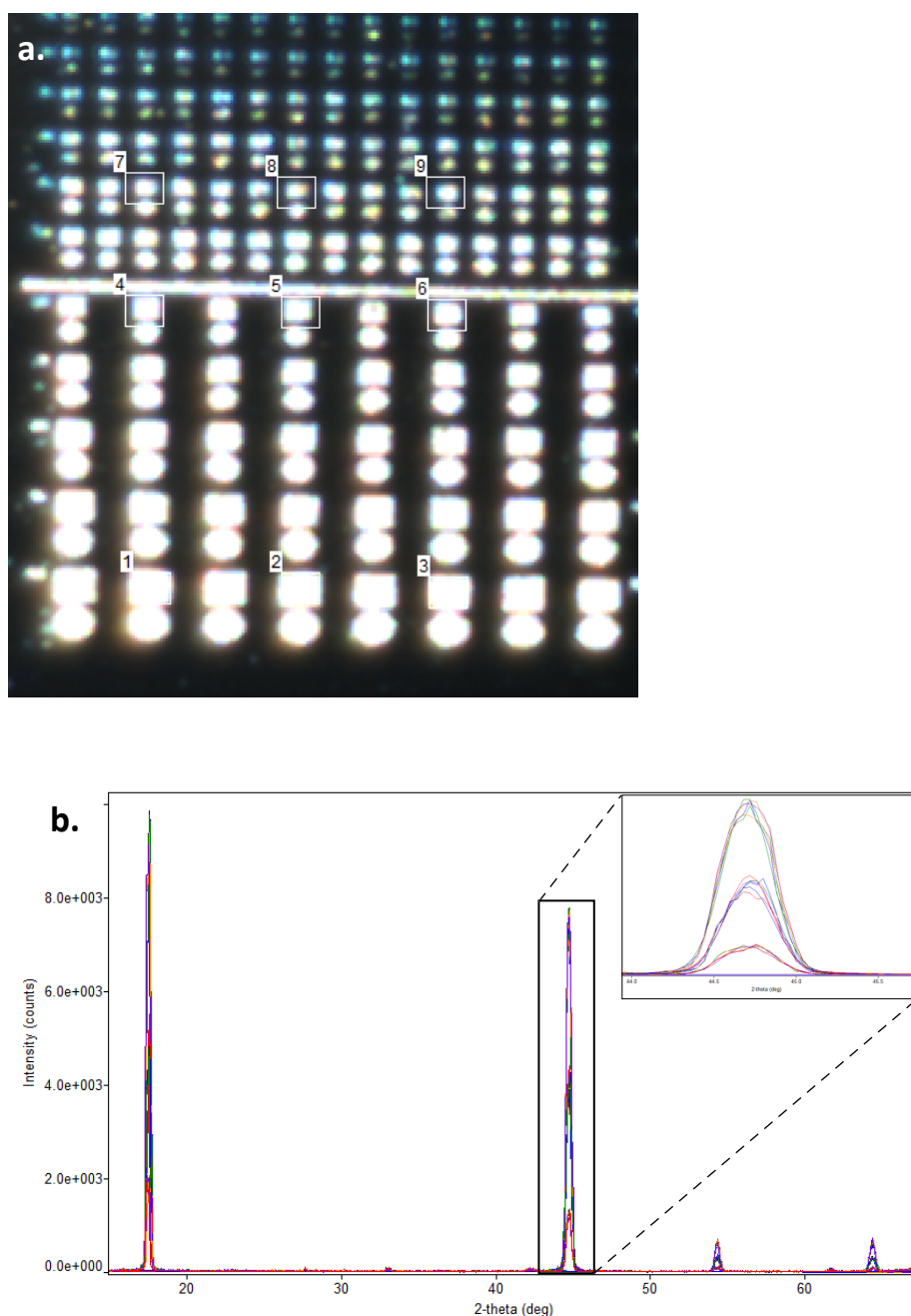


Figure S5. a. Optical microscope view of Bi_2Te_3 array, with areas of beam for microfocus X-ray scans highlighted. **b.** Overlaid patterns from 9 different wells in Bi_2Te_3 array. Insert shows zoomed in 0 0 15 peak. In each case data plus fit line are shown.

Equation S1. Pole figure analysis. Calculation of inclination of the diffraction vector to measure the 0 1 5 reflection if <0 0 1> is inclined at the surface normal with $\alpha_{001} = 90^\circ$:

$$\alpha_{015} = 90 - \tan^{-1}\left(\frac{c/5}{a \cos 30}\right)$$

$$a = 4.4$$

$$c = 30.4$$

$$\text{Therefore } \alpha_{015} = 32.1^\circ$$